MEG03-005

MAY 1 6 2007

appl. no. 10/796,427

May 11, 2007

To:

Commissioner for Patents

P.O. Box 1450

Alexandria, VA 22313-1450

Fr:

Stephen B. Ackerman, Reg. No. 37,761

28 Davis Avenue

Poughkeepsie, N.Y. 12603

Subject:

Serial No.

10/796,427

03/09/04

MOU-SHIUNG LIN

"WIREBOND PAD FOR SEMICONDUCTOR CHIP

OR WAFER"

Grp. Art Unit: 2822

LEWIS, MONICA

RESPONSE TO FINAL OFFICE ACTION

Dear Sir:

In response to the Office Action mailed February 12, 2007, please consider the remarks as follows:

CERTIFICATE OF MAILING

I hereby certify that this correspondence is being deposited with the United States Postal Service as first class mail in an envelope addressed to: Commissioner for Patents, P.O. Box 1450, Alexandria, VA 22313-1450, on May 14, 2007.

Stephen B. Ackerman, Reg. No. 37,761

Signature

Date 5/14/03